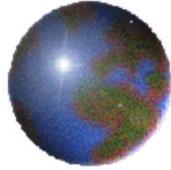


情報検索委員会
East meets West 2014
PDG IMPACT Meeting
訪問団の派遣報告



**6/24 関東部会
6/27 関西部会**

Creating IP Vision for the World



今回の訪問までの経緯

- ◆ 2012, 2013年： EPO PIC に参加

(Patent Information Conference)

- PDGのWG “IMPACT” と連携開始

(Impact of patent laws on documentation)

- EPO・USPTOの特許分類責任者と意見交換

CPCとFIが乖離する問題を提起



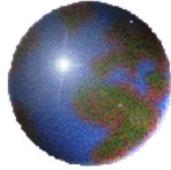
- ◆ 2014年： PDGから65th IMPACT meeting に出席要請

EPO East meets West 2014 と併せて参加

- CPCとFI/Fチームの調和実現に向けて、そのメリットをPDG及びEPOに
対して、日本特許ユーザーの代表としてプレゼンテーション

CPCとFIの調和を推進





East meets West 2014

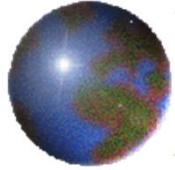
● 概要

- 日程、場所: 4/10-11 @ Hotel Savoyen, Vienna
- 主催:EPO
- 参加: 特許ユーザー、ツールベンダー
各国特許庁関係者(アジア等含む)
※30カ国から約110名参加



● 内容

- OCR
 - 電子データ化されていない古い特許をサーチする需要
 - 読み取りの精度の課題と解決への展望(発表: 発明通信社)
- 機械翻訳
 - 中国語、韓国語、日本語を英語で読む需要
 - Google - EPO の機械翻訳プロジェクトの紹介(発表: EPO)
 - 化学式名称の翻訳エンジンの紹介(発表: Chemaxon)
- EAST countries
 - ASEAN特許事情(発表: インドネシア、フィリピン、カンボジア各國庁)
 - アラブ特許事情(発表: ARABPAT、サウジアラビア特許庁)



PDG IMPACT meeting 2014

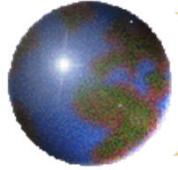
● 概要

- 日程、場所: **4/10-11 @ Hotel Linda, Vienna**
- 主催: **PDG IMPACT**
- 参加: **IMPACT メンバー(特許ユーザー&ベンダー)、EPO
IPPH, JPO, Japio, JIPA** (約50名参加)
- 趣旨: **IMPACT メンバーの特許検索の課題をEPO等の特許庁と共有する場**

● 内容

- 機械翻訳の精度
- リーガルステータスの取得
- ファミリー情報の取得
- サイテーションの取得
- 出願人の記載揺れ
- PCT各国移行の情報の取得
- 各国のカバレッジ
- CPCのグローバルスタンダード化に対するJPOのFI/F termの独自性





CPCとFI, Fタームの調和を要望

◆ PDG IMPACT meeting におけるプレゼンテーション



Background

- CPC entered into force in the EPO and US in January 2013. As a result, we can search in documents but also US documents by using the classification system. The IP offices of China have decided to employ the CPC in some technical fields where the Chinese patent classification is not yet available. In this situation, we expect that the CPC will be very useful to users.

The CPC is useful for searching US and Chinese patent documents, because the CPC is based on international classification. However, the CPC has room for improvement in some technical fields where the Chinese patent classification is not yet available. In this situation, we expect that the CPC will be very useful to users.

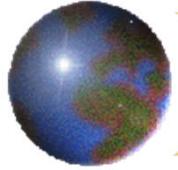
◆ EPO 分類担当者とのディスカッション

- JPO 分類担当者も含めて
- JETRO 田名部様のセッティング





以下、プレゼンテーション抜粋



プレゼンテーション概要

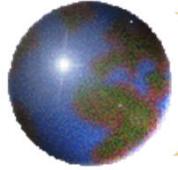
● 我々の考えるCPC分類への期待をPDGと共有

■ CPC分類とFI分類の比較

- いくつかの分野ではFI, Ftermを参考とし、CPC分類を更に細分類することが可能

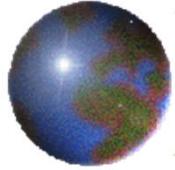
■ CPC分類体系にFI/Fterm分類を吸収する期待

- 特許情報ユーザーだけでなく世界各国の特許庁も詳細検索が可能となるメリット



背景

- ◆ CPC分類はEPOとUSPTOがリードし2013年1月に運用開始された。その結果、我々はCPCという単一の分類体系を用いてEP特許もUS特許も検索できるようになった。
- ◆ 中国特許庁および韓国特許庁は、いくつかの技術分野においてCPC分類体系を採用することを決定した。このような状況から我々はCPC分類はユーザーによってより有益に活用できると期待している。
- ◆ CPC分類はECLA分類やUSPC分類をベースとして構築されているため、検索において活用しやすい。
しかしながら、CPC分類は、中国特許や韓国特許の件数が多いいくつかの技術分野において改善の余地があると考えている。



CPC分類とFI分類の比較

● 特許分類数の比較

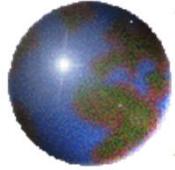
- A61B3/ の分類は、CPC分類においてもFI分類においても有益である。
[<APPENDIX 1>](#)
- B41J2/ の分類は、CPC分類がFI分類より多く分類項目があり、CPC分類が比較的有益に活用できる
[<APPENDIX 2>](#)
- H01L21/302 の分類は、FI分類がCPC分類より多く分類項目があり、FI分類が比較的有益に活用できる
[<APPENDIX 3>](#)

● 分類項目視点の比較

- A61F18/ の分類は、FI分類の分類視点がCPC分類よりも適切であると考えられ、FI分類が比較的有益に活用できる。[<APPENDIX 4>](#)

● アジア圏の重要特許の検索容易性の比較

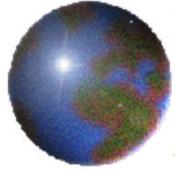
- 特に中国特許や韓国特許を検索する際に、FI分類はいくつかの技術分野においてより有益に活用できる。
[<APPENDIX 5>](#)



CPC分類とFI分類の比較

◆ 分類定義の比較

- いくつかのCPC分類には“Fterm”の分類定義がそのまま含まれている。
[<APPENDIX 6>](#)
- D07B 2000 seriesは CPC分類とFterm分類の親和性が高い。
[<APPENDIX 7>](#)



私たちのCPCに対する期待

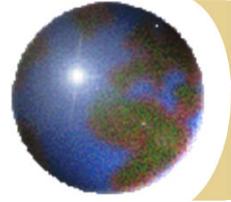
- 日本固有の特許分類であるFI分類は、いくつかの技術分野においてCPC分類よりも多くの分類項目を有する。それら技術分野は中国特許や韓国特許の件数が多い分野でもある。

したがって、幾つかの技術分野においては中国・韓国特許を検索するにあたりFI分類が有益に活用できる。

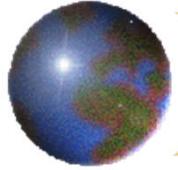
特許分類のハーモナイズの視点から、CPC分類の良い箇所をFI分類に取込むと同時に、FI分類の良い箇所をCPC分類に取込むことが、特許情報ユーザーにとって有益であると考える。

- FIだけでなくFtermも有益な分類体系であり、CPC 2000シリーズがFterm分類体系を取込むことを提案した。

**FI/Fterm分類とCPC分類のハーモナイズが
さらに促進されることを期待します**



以上、プレゼンテーション抜粋



今後のPDGとのコラボレーション

◆ CPC

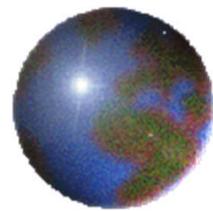
■ EPO, JPO のマターに移行

- EPO
 - PDG のBOARD会議で方針を検討してアクションを起こす
- JPO
 - JIPAとJPO特許分類企画班との意見交換会(5/23)

◆ その他

■ 情報検索委員会WGテーマのシェアリングを検討していく

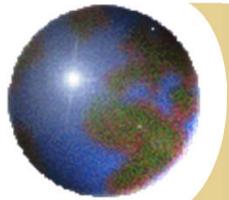
- リーガルステータス
- ASEAN
- 価値評価



*We keep working
Welcome your
advice!*



Creating IP Vision for the World



Appendix

**Comparison between
CPC and FI, Ftem**

<APPENDIX 1>

Analysis for A61B3 (Apparatus for testing the eyes)

Study on comparison between the CPC and the FI (in terms of the number of entries and the viewpoint). Some parts of the CPC will be improved by introducing the entries of the FI.

CPC entry -> 64

:

A61B 3/14 . . Arrangements specially adapted for eye photography
(apparatus or arrangements for taking photographs per se G03B)
A61B 3/145 . . . {by video means}

A61B 3/15 . . . with means for aligning, spacing or blocking spurious reflection; {with means for relaxing}

A61B 3/152 . . . {for aligning}

A61B 3/154 . . . {for spacing}

A61B 3/156 . . . {for blocking}

A61B 3/158 { of corneal reflection}

These FI parts could be merged into here.

=

FI entry -> 61

:

A61B 3/14	.. with means for attaching cameras thereto
A61B 3/14 A	Eye grounds camera
A61B 3/14 B	• Line of sight induction
A61B 3/14 C	• Removal of the harmful light
A61B 3/14 D	• Change in the angle of field
A61B 3/14 E	• Focusing
A61B 3/14 F	• Shaft setting, alignment
A61B 3/14 G	• Fluorescent photography
A61B 3/14 H	• Lighting with infrared ray
A61B 3/14 J	• Cubic, both eyes, demonstration
A61B 3/14 K	• Observation photography system
A61B 3/14 L	.. Optical system
A61B 3/14 M	.. Electrical measurement unit
A61B 3/14 Z	Others

[return](#)

< APPENDIX 2> Analysis for B41J2(Ink Jet Printer)

CPC entry -> 220

B41J 2/01 . . Ink jet
B41J 2/015 . . . characterised by the jet generation process (B41J 2/21)
B41J 2/02 . . . generating a continuous ink jet
B41J 2/025 . . . by vibration
B41J 2/03 . . . by pressure
B41J 2/035 . . .
B41J 2/04 . . .
B41J 2/045 . . .
B41J 2/04501 . . .
B41J 2/04503 . . .
B41J 2/04505 . . . { aiming at correcting alignment}
B41J 2/04506 . . . { aiming at correcting manufacturing tolerances}
B41J 2/04508 . . . {}
B41J 2/0451 . . . { fo}
B41J 2/04511 . . . { fo}
B41J 2/04513 . . . { fo}
B41J 2/04515 . . . { preventing overheating}
B41J 2/04516 . . . { preventing formation of satellite drops}
B41J 2/04518 . . . { reducing costs}
B41J 2/0452 . . . { reducing demand in current or voltage}
B41J 2/04521 . . . { reducing number of signal lines needed}
B41J 2/04523 . . . { reducing size of the apparatus}
B41J 2/04525 . . . { reducing occurrence of cross talk}
B41J 2/04526 . . . { controlling trajectory}
B41J 2/04528 . . . { aiming at}

The number of the CPC entries is larger than that of the FI.
Because of the FI is based on the older IPC version!

Entry FI	
1	B41J 3/00 101
	• Recording head
	B41J 3/00 102
	• Recording device drive
	B41J 3/02
	• for building-up characters by writing or by
	B41J 3/04
	• by moving stylus or their equivalent or writing jets
	B41J 3/04 101
	•
8	B41J 3/04 102 H Head cleaning
9	B41J 3/04 102 P Unnecessary ink collection
13	B41J 3/04 103 B • Bubble jet (R) type
14	B41J 3/04 103 D • Diaphragm type
15	B41J 3/04 103 C using air flow
16	B41J 3/04 103 E Vibration control system (continuous type)
17	B41J 3/04 103 F Stylus system using a magnetic fluid
18	B41J 3/04 103 G Electrostatic or magnetic suction system
19	B41J 3/04 103 S using thermally fused ink (solid ink)
20	B41J 3/04 103 T (using the ink carrier such as the porous sheet
21	B41J 3/04 103 H Head assembly or manufacture
22	•
27	B41J 3/04 104 B Electrical field control type
28	B41J 3/04 104 C Phase search or control (takes precedence over F)
29	B41J 3/04 104 D Flying control against relative moving between the
30	B41J 3/04 104 F Flying control using feedback control
31	B41J 3/04 104 G Flying control using distortion correction
32	B41J 3/04 104 H Flying control characterized by processing of the dot
33	B41J 3/04 104 E Charging or deviation electrode
34	B41J 3/04 104 K Detection electrode or detection device
35	B41J 3/04 104 X Flying control for concentration or gradation
36	B41J 3/04 104 Z Others

The CPC is superior to the FI in this part !

B41J 2/2132 . . . { Print quality control characterised by dot disposition,
B41J 2/2135 . . . { Alignment of dots (adjustments by bodily moving prin
B41J 2/2139 . . . { Compensation for malfunctioning nozzles creating c
B41J 2/2142 . . . { Detection of malfunctioning nozzles (for cleaning p
B41J 2/2146 . . . { for line print heads}

[return](#)

< APPENDIX 3>

Analysis for H01L21/302 (Dry etching of semiconductors)

CPC entry -> 4

H01L 21/302 to change their surface-physical characteristics or shape, e.g. etching, polishing, cutting
H01L 21/304 Mechanical treatment, e.g. grinding, polishing, cutting {(H01L 21/30625 takes precedence)}
H01L 21/3043 Mechanical treatment, e.g. grinding, polishing, cutting {(H01L 21/30625 takes precedence)}
H01L 21/3046 {using blasting, e.g. sand-blasting (H01L 21/2633 takes precedence)}

Fl entry -> 37

H01L 21/302 to change their surface-physical characteristics or shape, e.g. etching, polishing, cutting [2]
H01L 21/302 100 Plasma etching
H01L 21/302 101 Plasma etching systems
H01L 21/302 101 B	Parallel flat plate systems (including capacitive coupling type, RIE, two-frequency systems)
H01L 21/302 101 C	Inductive coupling systems (includng TCP (R), ICP, helicon wave systems)
H01L 21/302 101 D	Microwave and UHF wave exciting systems (includng ECR, cavity resonance systems; including systems generally using microwaves)
H01L 21/302 101 E	Local plasma (including atmospheric discharge, PACE, chemical vapor machining (CVM))

The number of entries in this part of the CPC is insufficient, as compared to the Fl.

This part of the CPC is not sufficiently useful compared to the Fl.

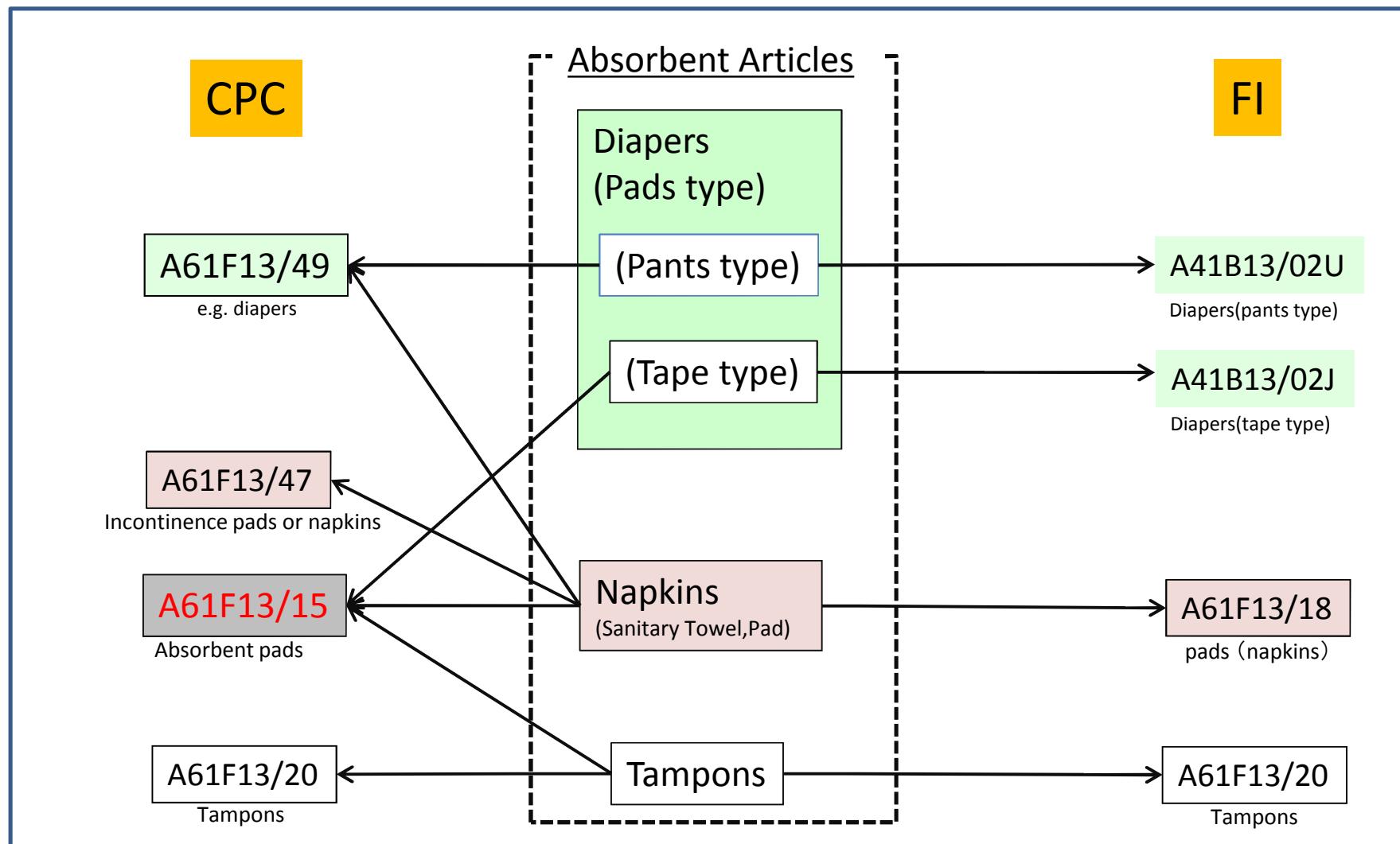
H01L 21/302 101 F	mechanisms, electrostatic chucks, pipes, process-to-process transportation, process simulation, combination with other semiconductor manufacturing facilities)
H01L 21/302 101 H	• System cleaning (including wall cleaning, aging)
H01L 21/302 101 M	• Improvement of maintainability (technology necessary for disassembly and cleaning
H01L 21/302 101 R	• Back side gas supply (including technologies for supplying thermally conductive gas to the portion that will closely contact back face of treated substrate to improve thermal conduction)
H01L 21/302 101 Z	Others
H01L 21/302 102 Substrate cleaning (plasma cleaning including substrate surface cleaning; plasma cleaning H01L21/302 and 106)
H01L 21/302 103 End point detection and monitoring (for etching end point detection and plasma monitoring (spectroscopic analysis, mass detection, detected waveform processing))
H01L 21/302 104 Etched substrate

[return](#)

< APPENDIX 4 >

Analysis for A61F13 (Bandages, dressings or absorbent pads)

This part of the CPC is not sufficiently useful because one article may fall into different entries in the CPC. The FI is useful because one article falls into one entry in the FI.



< APPENDIX 5 > SECTIONS WITH INSUFFICIENT NUMBER OF ENTRIES IN CPC

This part of the CPC is not sufficiently useful, particularly for searching Chinese and Korean patent documents. In star-marked sections, an insufficient number of entries may cause difficulties in the process of searching Chinese and Korean patent documents.

Classification Code	Number of Entries(FI)	Number of Entries(CPC)	Code name	Number of documents (JP)	Number of documents (EP)	Number of documents (CN and KR)	Number of documents(CN and KR) per a FI entry.	Number of documents(CN and KR) per a CPC entry.	Mark
A01C11/	213	6	Transplanting machines	419	5	1057	5	176	★
B32B33/	47	1	Layered products characterised by particular properties or particular surface features,	177	54	2831	60	2831	★★
B32B27/	78	37	Layered products essentially comprising synthetic resin	4966	1264	12670	162	342	★★
B60R16/	192	27	Electric or fluid circuits or arrangements of elements thereof specially adapted for vehicles	2513	358	4126	21	153	★
B60R21/	304	80	Arrangements or fittings on vehicles for protecting or preventing injuries to occupants or pedestrians in case of accidents or other traffic risks	2245	534	3705	12	46	
F24C7/	267	23	Stoves or ranges heated by electric energy	358	202	1728	6	75	
F25B1/	230	9	Compression machines, plant or systems with non-reversible cycle	1180	246	1217	5	135	★
G06F3/	755	277	Input arrangements for transferring data to be processed into a form capable of being handled by the computer	15298	4225	35091	46	127	★
G09F9/	483	18	Indicating arrangements for variable information in which the information is built-up on a support by selection or combination of individual elements	3745	267	5885	12	327	★★
H02K1/	114	49	Details of the magnetic circuit	1645	511	6445	57	132	★

< APPENDIX 6 >
Definitions including word “Fterm” in CPC

**There are 154 Sub Classes which include a word s.t.
“Fterm” or “F-term”**

CPC		Fterm	
A47L15/0081	[N: with vertical sliding closing doors, e.g. hood-type dishwashers]	3B082/BB05	Vertical sliding unit (Japanese F-term)
A47L15/4253	[N: Supporting arrangements for the casing, e.g. rollers or supporting legs]	3B155/DA13	Legs or bases for the casing of laundry washing machines (Japanese F-term)
A47L15/48	Drying arrangements	3B082/EE00	Drying apparatuses (Japanese F-term)
A47L15/488	[N: Connections of the tub with the ambient air, e.g. air intake or venting arrangements]	3B082/BE00	Air intake and venting (Japanese F-term)
A47L15/50	Racks	3B082/FF00	Racks (Japanese F-term)
A63F7/022	[N: Pachinko]	2C088/AA01	Standard achinko games (i.e. vertical pinball machines) (FTerm)
B25J1/00	Manipulators positioned in space by hand (of master-slave type B25J3/00; micromanipulators B25J7/00)	3C007/BS29	Manual manipulators
B25J1/00	Manipulators positioned in space by hand (of master-slave type B25J3/00; micromanipulators B25J7/00)	3C007/XF00	Structures and purposes of manual manipulators
B25J1/02	articulated or flexible	3C007/XF01	Manual manipulators having a joint
B25J1/02	articulated or flexible	3C007/XF02	Flexible manual manipulators
B25J1/04	rigid, e.g. shelf-reachers [N: (without grippers A47F13/06)]	3C007/XF05	Tool hands
B25J1/04	rigid, e.g. shelf-reachers [N: (without grippers A47F13/06)]	3C007/XF06	Support hands
B25J1/12	having means for attachment to a support stand	3C007/XF03	Manual manipulator containing mounting device to support structure
B25J13/003	[N: by means of an audio-responsive input (audible safety signals B25J19/061)]	3C007/WB19	Control of robot by voice input
.....

< APPENDIX 7 >
CPC 2000 series are similar with Fterm

CPC 2000 series are
similar with Fterm

D07B ROPES OR CABLES IN GENERAL

<input type="checkbox"/> D07B 2201/00	Ropes or cables
<input type="checkbox"/> D07B 2205/00	Rope or cable materials
<input type="checkbox"/> D07B 2207/00	Rope or cable making machines
<input type="checkbox"/> D07B 2301/00	Controls
<input type="checkbox"/> D07B 2401/00	Aspects related to the problem to be solved or ad
<input type="checkbox"/> D07B 2501/00	Application field
<input type="checkbox"/> D07B 2801/00	Linked indexing codes associated with indexing

D07B 2205/00	Rope or cable materials	3B153CC	材料
D07B 2205/30	· Inorganic materials	CC41	. 無機材料
D07B 2205/3003	·· Glass	CC42	.. ガラス
D07B 2205/3007	·· Carbon	CC43	.. 炭素
D07B 2205/301	·· Ceramics	CC44	.. セラミック*
D07B 2205/3014	·· Asbestos	CC45	... 石綿(アスベスト)
D07B 2205/3017	·· Silicon carbides	CC46	... 炭化ケイ素(SiC)
D07B 2205/3021	·· Metals	CC51	. 金属材料
D07B 2205/3025	··· Steel	CC52	.. 鋼(スチール)
D07B 2205/3028	···· Stainless steel	CC53	.. ステンレス

3B153	ロープ又はケーブル一般	繊維・積層
	<u>D07B1/00-9/00</u>	

AA	AA00	BB	BB00	CC	CC00	DD	DD00	FF	FF00	GG	GG00	WW	WW00
	構造		素線の形状 又は構造		材料		製造方法/ 装置		用途		目的又は効 果		わら繩の製 造

[return](#)